



# N-Channel 30-V (D-S) MOSFET with Schottky Diode

PRODUCT SUMMARY					
V <sub>DS</sub> (V)	$R_{DS(on)}(\Omega)$	I <sub>D</sub> (A) <sup>a</sup>	Q <sub>g</sub> (Typ.)		
30	0.0085 at V <sub>GS</sub> = 10 V	17	18.8 nC		
30	0.0105 at V <sub>GS</sub> = 4.5 V	15.6	10.6110		

SCHOTTKY AND BODY DIODE PRODUCT SUMMARY				
V <sub>DS</sub> (V)	V <sub>SD</sub> (V)	I <sub>S</sub> (A)		
30	0.4 at 2 A	5 <sup>a</sup>		

		SO-8		
s	1		8	D
S	2		7	D
S	3		6	D
G	4		5	D
	'	Top View	ı	

Ordering Information: Si4636DY-T1-E3 (Lead (Pb)-free)

Si4636DY-T1-GE3 (Lead (Pb)-free and Halogen-free)

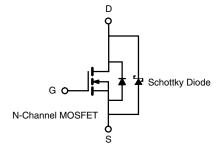
#### **FEATURES**

- Halogen-free According to IEC 61249-2-21 Available
- TrenchFET<sup>®</sup> Power MOSFET
- 100 % R<sub>g</sub> and UIS Tested

#### **APPLICATIONS**

- Notebook Logic DC/DC
  - Low Side





Parameter		Symbol	Limit	Unit	
Drain-Source Voltage	$V_{DS}$	30	V		
Gate-Source Voltage		$V_{GS}$	± 16	<b>v</b>	
	T <sub>C</sub> = 25 °C		17.0	A	
Continuous Drain Current (T <sub>.I</sub> = 150 °C)	T <sub>C</sub> = 70 °C	I <sub>D</sub>	13.5		
Continuodo Brain Cancin (1) = 100 °C)	T <sub>A</sub> = 25 °C	טי	12.7 <sup>b, c</sup>		
	T <sub>A</sub> = 70 °C		10.2 <sup>b, c</sup>		
Pulsed Drain Current		I <sub>DM</sub>	60	A	
Continuous Source-Drain Diode Current	T <sub>C</sub> = 25 °C	I <sub>S</sub>	5.0		
Continuous Source-Diam Diode Current	T <sub>A</sub> = 25 °C	'8	2.3 <sup>b, c</sup>		
Single Pulse Avalanche Current	L = 0.1 mH	I <sub>AS</sub>	20		
Single Pulse Avalanche Energy		E <sub>AS</sub>	20	mJ	
	T <sub>C</sub> = 25 °C		4.4	W	
Maximum Power Dissipation	T <sub>C</sub> = 70 °C	$P_{\mathrm{D}}$	2.8		
Maximum 1 ower Biosipation	T <sub>A</sub> = 25 °C	' D	2.5 <sup>b, c</sup>	VV	
	T <sub>A</sub> = 70 °C		1.6 <sup>b, c</sup>		
Operating Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	- 55 to 150	°C		

THERMAL RESISTANCE RATINGS							
Parameter		Symbol	Тур.	Max.	Unit		
Maximum Junction-to-Ambient <sup>b, d</sup>	t ≤ 10 s	R <sub>thJA</sub>	40	50	°C/W		
Maximum Junction-to-Foot (Drain)	Steady State	$R_{thJF}$	23	28	] 5/11		

#### Notes:

- a. Based on  $T_C = 25$  °C.
- b. Surface Mounted on 1" x 1" FR4 board.
- c. t = 10 s
- d. Maximum under Steady State conditions is 90 °C/W.

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Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static		'		<u> </u>			
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	30			٧	
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	1.0		2.5	٧	
Gate-Source Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 16 \text{ V}$			± 100	nA	
Zava Cata Valtaga Dvain Curvent	I <sub>DSS</sub>	V <sub>DS</sub> = 30 V, V <sub>GS</sub> = 0 V		0.19	1	mA	
Zero Gate Voltage Drain Current		V <sub>DS</sub> = 30 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 100 °C		14	100		
On -State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	30			Α	
Durin Course Co. Otata Basistana a	B	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 10 A		0.0067	0.0085	Ω	
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = 4.5 V, I <sub>D</sub> = 8 A		0.008	0.0105		
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 10 A		55		S	
Dynamic <sup>b</sup>							
Input Capacitance	C <sub>iss</sub>			2635		pF	
Output Capacitance	C <sub>oss</sub>	$V_{DS} = 15 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		435			
Reverse Transfer Capacitance	C <sub>rss</sub>	1		138			
Total Cata Charge	0	V <sub>DS</sub> = 15 V, V <sub>GS</sub> = 10 V, I <sub>D</sub> = 10 A		40	60	nC	
Total Gate Charge	$Q_g$	V <sub>DS</sub> = 15 V, V <sub>GS</sub> = 4.5 V, I <sub>D</sub> = 10 A		18.8	30		
Gate-Source Charge	$Q_{gs}$			7.1			
Gate-Drain Charge	$Q_gd$			4.7			
Gate Resistance	$R_g$	f = 1 MHz		1.3	2.0	Ω	
Turn-On Delay Time	t <sub>d(on)</sub>			32	50		
Rise Time	t <sub>r</sub>	$V_{DD} = 15 \text{ V}, R_{L} = 1.5 \Omega$		87	135	- ns	
Turn-Off Delay Time	t <sub>d(off)</sub>	$I_D \cong 10 \text{ A}, V_{GEN} = 4.5 \text{ V}, R_g = 1 \Omega$		43	65		
Fall Time	t <sub>f</sub>			19	30		
Turn-On Delay Time	t <sub>d(on)</sub>			12	20	115	
Rise Time	t <sub>r</sub>	$V_{DD} = 15 \text{ V}, R_{L} = 1.5 \Omega$		12	20		
Turn-Off Delay Time	t <sub>d(off)</sub>	$I_D \cong 10 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 1 \Omega$		33	50		
Fall Time	t <sub>f</sub>			9	16		
<b>Drain-Source Body Diode and Schottky</b>	Characterist						
Continuous Source-Drain Diode Current	I <sub>S</sub>	T <sub>C</sub> = 25 °C			5.0	Α	
Pulse Diode Forward Current <sup>a</sup>	I <sub>SM</sub>				60		
Body Diode Voltage	$V_{SD}$	I <sub>S</sub> = 2 A		0.36	0.41	V	
Body Diode Reverse Recovery Time	t <sub>rr</sub>			28	45	ns	
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>	- I <sub>F</sub> = 4 A, dl/dt = 100 A/μs, T <sub>J</sub> = 25 °C		19	30	nC	
Reverse Recovery Fall Time	t <sub>a</sub>	η – τ Λ, αι/αι – 100 Λ/μο, 1 <sub>J</sub> – 25 0		14		nc	
Reverse Recovery Rise Time	t <sub>b</sub>			14		ns	

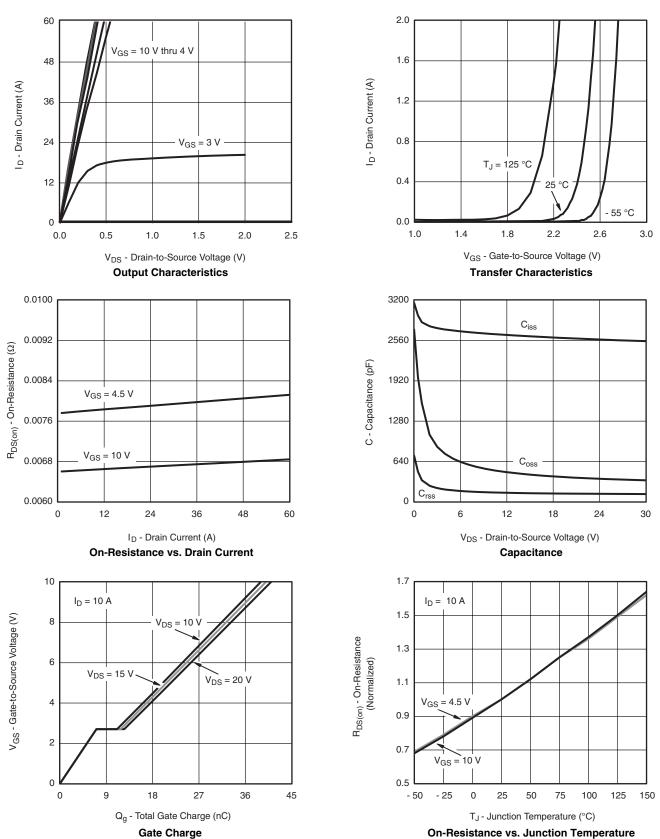
- a. Pulse test; pulse width  $\leq$  300  $\mu$ s, duty cycle  $\leq$  2 %. b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



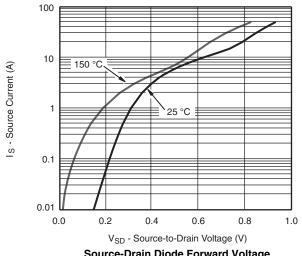


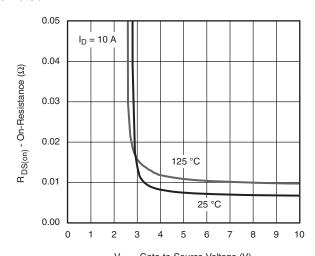
### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



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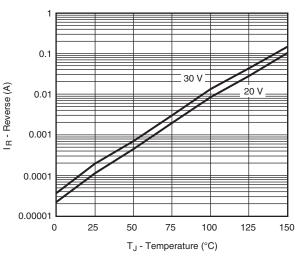
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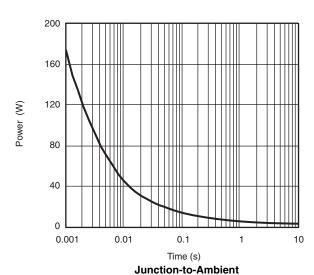




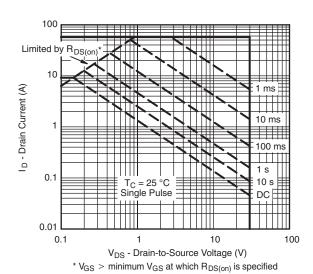
Source-Drain Diode Forward Voltage







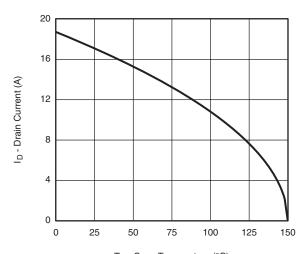
Reverse Current (Schottky)



Safe Operating Area

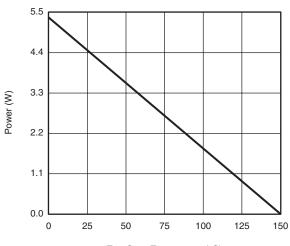


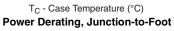
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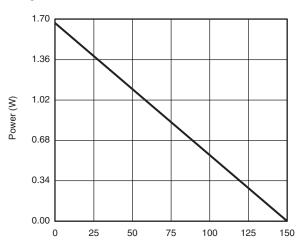


T<sub>C</sub> - Case Temperature (°C)

#### **Current Derating\***







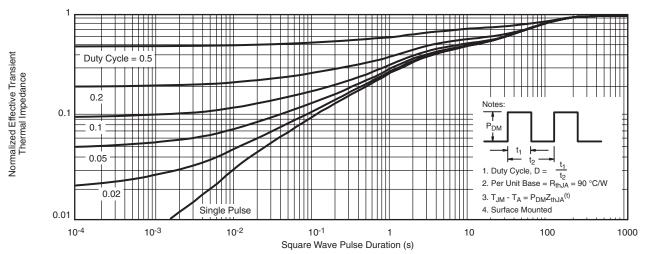
T<sub>A</sub> - Ambient Temperature (°C) **Power Derating, Junction-to-Ambient** 

<sup>\*</sup> The power dissipation  $P_D$  is based on  $T_{J(max)} = 150$  °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

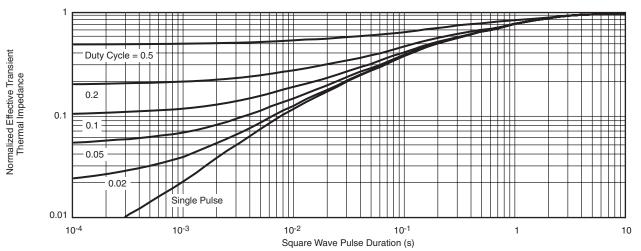
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#### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



#### Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Case

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